

DAFTAR PUSTAKA

- [1] G. Efendy, I. D. Handayani, N. F. Husni, and S. Habibah, "Konduktivitas Listrik Poly (Lactic Acid) dengan Variasi Bahan Isian Karbon : Review," vol. 5, no. 1.
- [2] Marwanto, "Sifat Mekanik Komposit Berbasis Poli Asam Laktat (PLA) dan Serat Selulosa Tandan Kosong Kelapa Sawit (Mechanical Properties Composite Based Poly Lactic Acid (PLA) And Cellulose Fiber Of Oil Palm Empty Fruit Bunches)," vol. 5, no. 2, pp. 412–417, 2017.
- [3] Pritiansyah, Hardiansyah, and Sugiyarto, "Manutech : Jurnal Teknologi Manufaktur Optimasi Parameter Proses 3D Printing FDM Terhadap Akurasi Dimensi Menggunakan Filament Eflex," *Manutech J. Teknol. Manufaktur*, vol. 11, no. 01, pp. 0–7, 2019.
- [4] Rahmayetty, N. Kanani, and E. Yudo, "Pengaruh Penambahan PLA pada Pati Terplastisasi Gliserol Terhadap Sifat Mekanik Blend Film," *J. Umj*, pp. 1–9, 2018.
- [5] K. Eko Putra, "Pengaruh Kekuatan Tarik Dan Tekan Pada Bahan di 3D Printer," 2019.
- [6] H. Tondi, "Rancang Bangun Mesin Ekstruder Filamen 3D Printer," *Skripsi Tek. Mesin, Fak. Teknol. Ind. Univ. Islam Indones.*, pp. 1–50, 2019.
- [7] T. F. Da Silva, F. Menezes, L. S. Montagna, A. P. Lemes, and F. R. Passador, "Synergistic effect of adding lignin and carbon black in poly(lactic acid)," *Polimeros*, vol. 30, no. 1, 2020, doi: 10.1590/0104-1428.06819.
- [8] A. Pranayuda, "Pengaruh Fraksi Volume Serbuk Aluminium Terhadap Kemampuan Menghantarkan Panas Komposit Serbuk Aluminium-Epoksi The Influence of Volume Aluminum Powder Fraction to Heat Transfer of Aluminum Powder-Epoxy Composite Presented as Partial Fulfillment of the Re," 2007.

- [9] D. Oktavian, B. Arifvianto, and M. Mahardika, “Ekstruksi Dan Karakterisasi Filamen Komposit Polylactid Acid (Pla) / Carbon Nano Tube (Cnt),” *J. Mater. Teknol. Proses War. Kemajuan Bid. Mater. Tek. Teknol. Proses*, vol. 2, no. 2, p. 12, 2021, doi: 10.22146/jmtp.70481.
- [10] Irzaman, R. Erviansyah, H. Syafutra, A. Maddu, and Siswadi, “Oksida (BFST) Menggunakan Metode Chemical Solution Deposition,” *Berk. Fis.*, vol. 13, no. 1, pp. 33–38, 2010.
- [11] K. A. Amdreamto and Z. A. Imam, “Pengukuran Resistivitas Pada Printed Circuit Board Dengan Menggunakan Metode Four Point Probe,” *Inov. Fis. Indones.*, vol. 7, no. 02, pp. 48–53, 2018.
- [12] D. Hidayat, R. Zulianto, B. M. Wibawa, and B. Y. Tumbelaka, “Pengembangan Pengukuran Sheet Resistance Film Tipis Menggunakan Metode Four Point Probe,” no. November, pp. 26–27, 2016.
- [13] M. P. Gutiérrez, H. Li, and J. Patton, “Thin Film Surface Resistivity In partial fulfillment of course requirements for Mate 210 Experimental Methods in Materials Engineering Fall 2002 Professor G. Selvaduray,” pp. 0–24, 2002.

